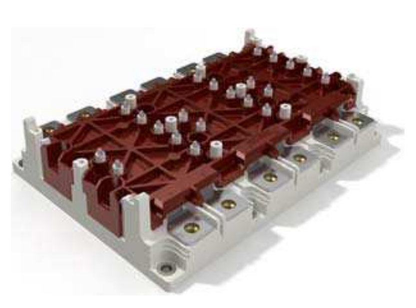


SKiM® 63

Trench IGBT Modules

SKiM606GD066HD

Features

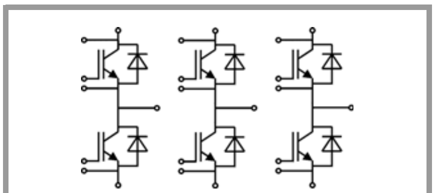
- IGBT 3 Trench Gate Technology
- Solderless sinter technology
- $V_{CE(sat)}$ with positive temperature coefficient
- Low inductance case
- Insulated by Al_2O_3 DCB (Direct Copper Bonded) ceramic substrate
- Pressure contact technology for thermal contacts
- Spring contact system to attach driver PCB to the control terminals
- High short circuit capability, self limiting to 6 x I_C
- Integrated temperature sensor

Typical Applications*

- Automotive inverter
- High reliability AC inverter wind
- High reliability AC inverter drives

Remarks

- Case temperature limited to T_s = 125°C max; T_c = T_s (for baseplateless modules)
- Recommended T_{op} = -40 … +150°C



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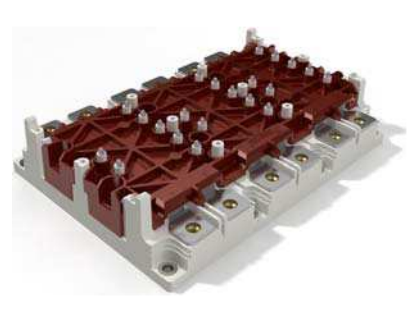
Absolute Maximum Ratings

Symbol	Conditions		Values	Unit
Inverter - IGBT				
V_{CES}	T_j = 25 °C		600	V
I_C	λ_{paste}=0.8 W/(mK) T_j = 175 °C	T_s = 25 °C	640	A
		T_s = 70 °C	510	A
I_C	λ_{paste}=2.5 W/(mK) T_j = 175 °C	T_s = 25 °C	768	A
		T_s = 70 °C	616	A
I_{Cnom}			600	A
I_{CRM}	I_{CRM} = 2 x I_{Cnom}		1200	A
V_{GES}			-20 ... 20	V
t_{psc}	V_{CC} = 360 V V_{GE} ≤ 15 V V_{CES} ≤ 600 V	T_j = 150 °C	6	µs
T_j			-40 ... 175	°C
Inverse - Diode				
I_F	λ_{paste}=0.8 W/(mK) T_j = 175 °C	T_s = 25 °C	445	A
		T_s = 70 °C	346	A
I_F	λ_{paste}=2.5 W/(mK) T_j = 175 °C	T_s = 25 °C	550	A
		T_s = 70 °C	432	A
I_{Fnom}			600	A
I_{FRM}	I_{FRM} = 2 x I_{Fnom}		1200	A
I_{FSM}	10 ms, sin 180°, T_j = 150 °C		2358	A
T_j			-40 ... 175	°C
Module				
$I_{t(RMS)}$	$T_{terminal}$ = 80 °C,		700	A
T_{stg}			-40 ... 125	°C
V_{isol}	AC sinus 50 Hz, t = 1 min		2500	V

Characteristics

Symbol	Conditions		min.	typ.	max.	Unit
Inverter - IGBT						
$V_{CE(sat)}$	I_C = 600 A V_{GE} = 15 V chiplevel	T_j = 25 °C		1.45	1.85	V
		T_j = 150 °C		1.70	2.10	V
V_{CE0}	chiplevel	T_j = 25 °C		0.90	1.00	V
		T_j = 150 °C		0.85	0.90	V
r_{CE}	V_{GE} = 15 V chiplevel	T_j = 25 °C		0.92	1.42	mΩ
		T_j = 150 °C		1.42	2.0	mΩ
$V_{GE(th)}$	V_{GE} = V_{CE}, I_C = 9.6 mA		5	5.8	6.5	V
I_{CES}	V_{GE} = 0 V, V_{CE} = 600 V, T_j = 25 °C			0.1	0.3	mA
C_{ies}	V_{CE} = 25 V V_{GE} = 0 V	f = 1 MHz		36.96		nF
C_{oes}		f = 1 MHz		2.304		nF
C_{res}		f = 1 MHz		1.096		nF
Q_G	V_{GE}=- 8 V...+ 15 V			4800		nC
R_{Gint}	T_j = 25 °C			0.5		Ω
$t_{d(on)}$	V_{CC} = 300 V I_C = 600 A $R_{G\ on}$ = 3 Ω $R_{G\ off}$ = 5 Ω di/dt_{on} = 5500 A/µs di/dt_{off} = 6200 A/µs V_{GE} = +15/-7.5 V	T_j = 150 °C		150		ns
t_r		T_j = 150 °C		120		ns
E_{on}		T_j = 150 °C		16		mJ
$t_{d(off)}$		T_j = 150 °C		1400		ns
t_f		T_j = 150 °C		75		ns
E_{off}		T_j = 150 °C		53		mJ
$R_{th(j-s)}$	per IGBT, λ_{paste}=0.8 W/(mK)			0.105		K/W
$R_{th(j-s)}$	per IGBT, λ_{paste}=2.5 W/(mK)			0.078		K/W



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SKiM606GD066HD

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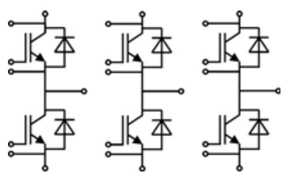

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Characteristics						
Symbol	**Conditions**		**min.**	**typ.**	**max.**	**Unit**
Inverse - Diode						
$V_F = V_{EC}$	I_F = 600 A chiplevel	T_j = 25 °C		1.60	1.85	V
		T_j = 150 °C		1.68	1.93	V
V_{F0}	chiplevel	T_j = 25 °C		1.00	1.10	V
		T_j = 150 °C		0.85	0.95	V
r_F	chiplevel	T_j = 25 °C		1.00	1.25	mΩ
		T_j = 150 °C		1.38	1.63	mΩ
I_{RRM}	I_F = 600 A di/dt_{off} = 5600 A/µs V_{GE} = +15/-7.5 V V_{CC} = 300 V	T_j = 150 °C		390		A
Q_{rr}		T_j = 150 °C		85		µC
E_{rr}		T_j = 150 °C		21		mJ
$R_{th(j-s)}$	per Diode, λ_{paste}=0.8 W/(mK)			0.201		K/W
$R_{th(j-s)}$	per Diode, λ_{paste}=2.5 W/(mK)			0.147		K/W
Module						
L_{CE}				9	13	nH
$R_{CC'+EE'}$	measured per switch	T_s = 25 °C		0.3		mΩ
		T_s = 125 °C		0.5		mΩ
w				761		g
Temperature Sensor						
R_{100}	T_{Sensor} = 100 °C (R_{25} = 5 kΩ)			339		Ω
$B_{100/125}$	$R_{(T)} = R_{100}exp[B_{100/125}(1/T-1/373)]$; T[K];			4096		K

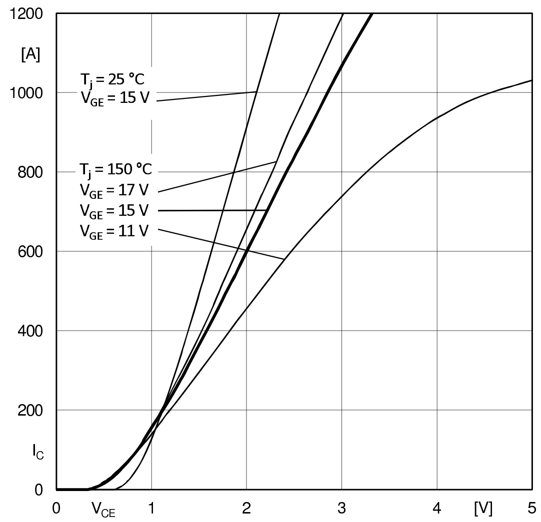


Fig. 1: Typ. output characteristic, inclusive $R_{CC'+ EE'}$

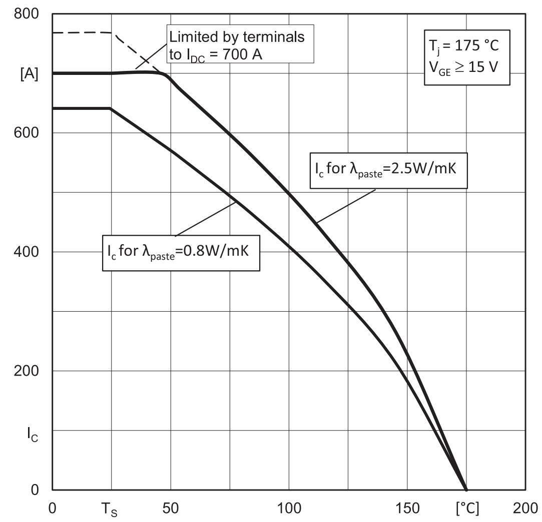


Fig. 2: Typ. rated current vs. temperature $I_C = f(T_S)$

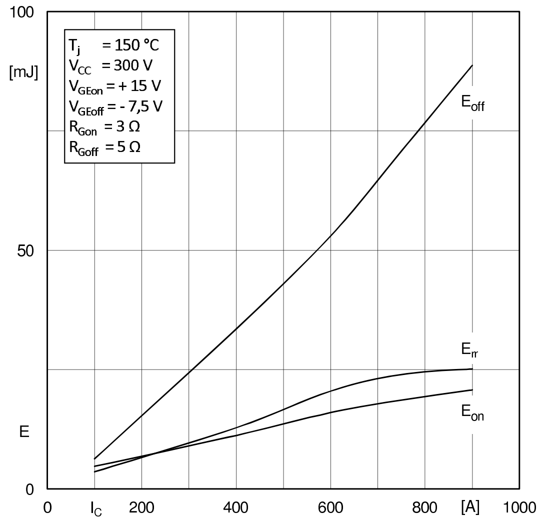


Fig. 3: Typ. turn-on /-off energy = f (I_C)

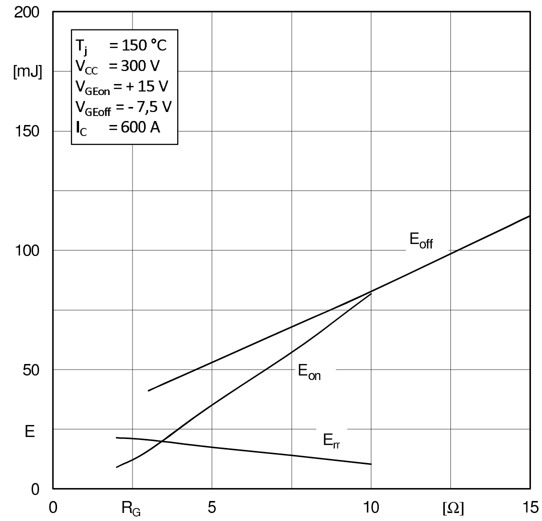


Fig. 4: Typ. turn-on /-off energy = f (R_G)

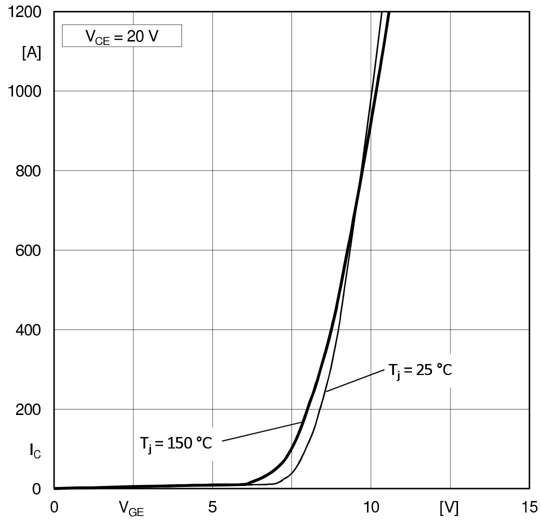


Fig. 5: Typ. transfer characteristic

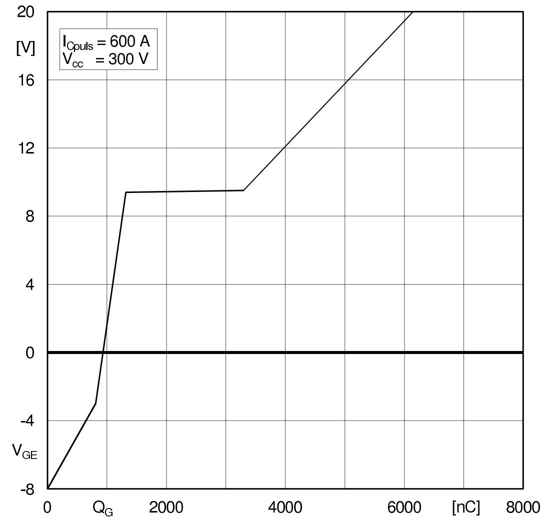


Fig. 6: Typ. gate charge characteristic

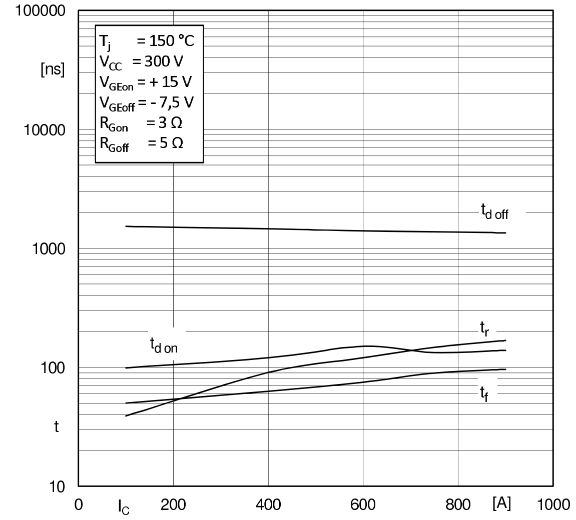


Fig. 7: Typ. switching times vs. I_C

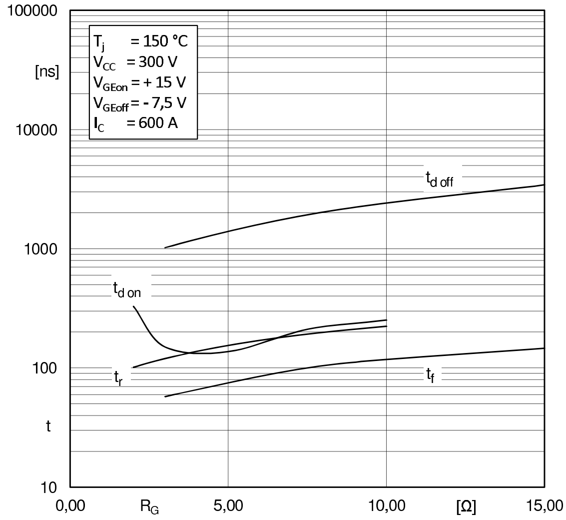


Fig. 8: Typ. switching times vs. gate resistor R_G

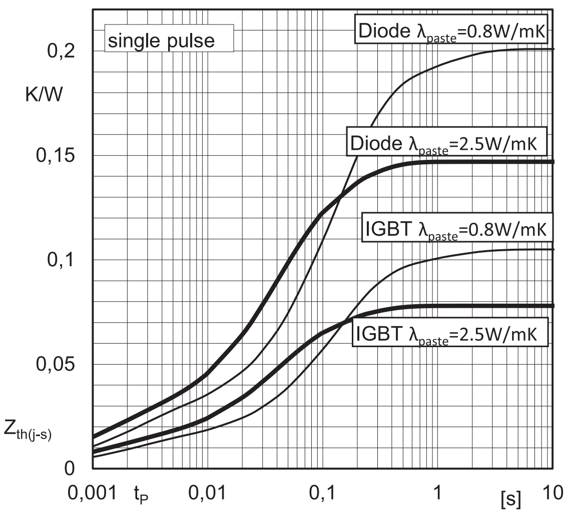


Fig. 9: Typ. transient thermal impedance

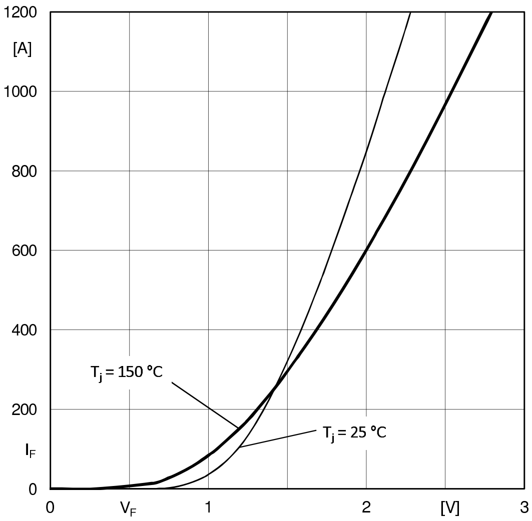


Fig. 10: Typ. CAL diode forward charact., incl. $R_{CC'+EE'}$

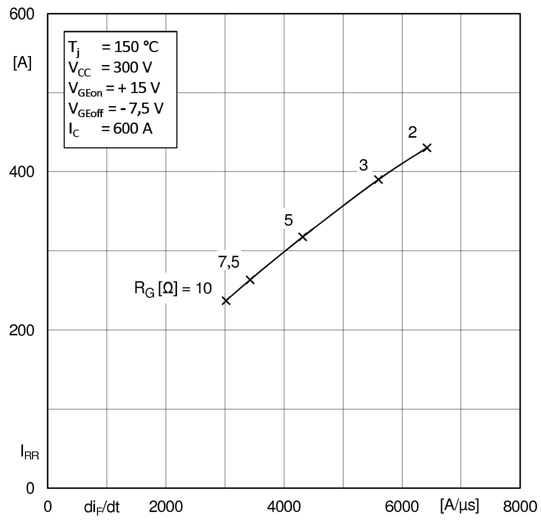


Fig. 11: Typ. CAL diode peak reverse recovery current

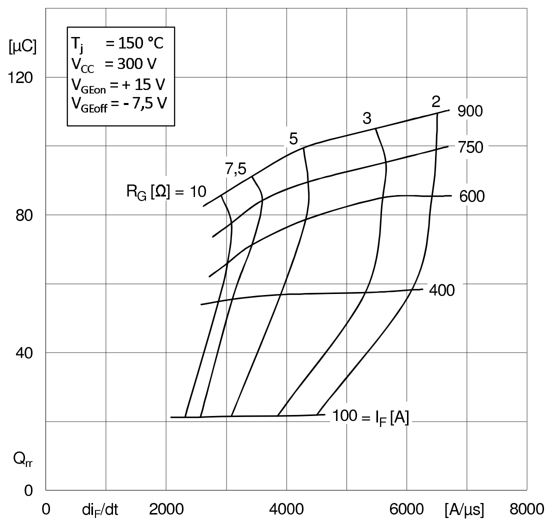
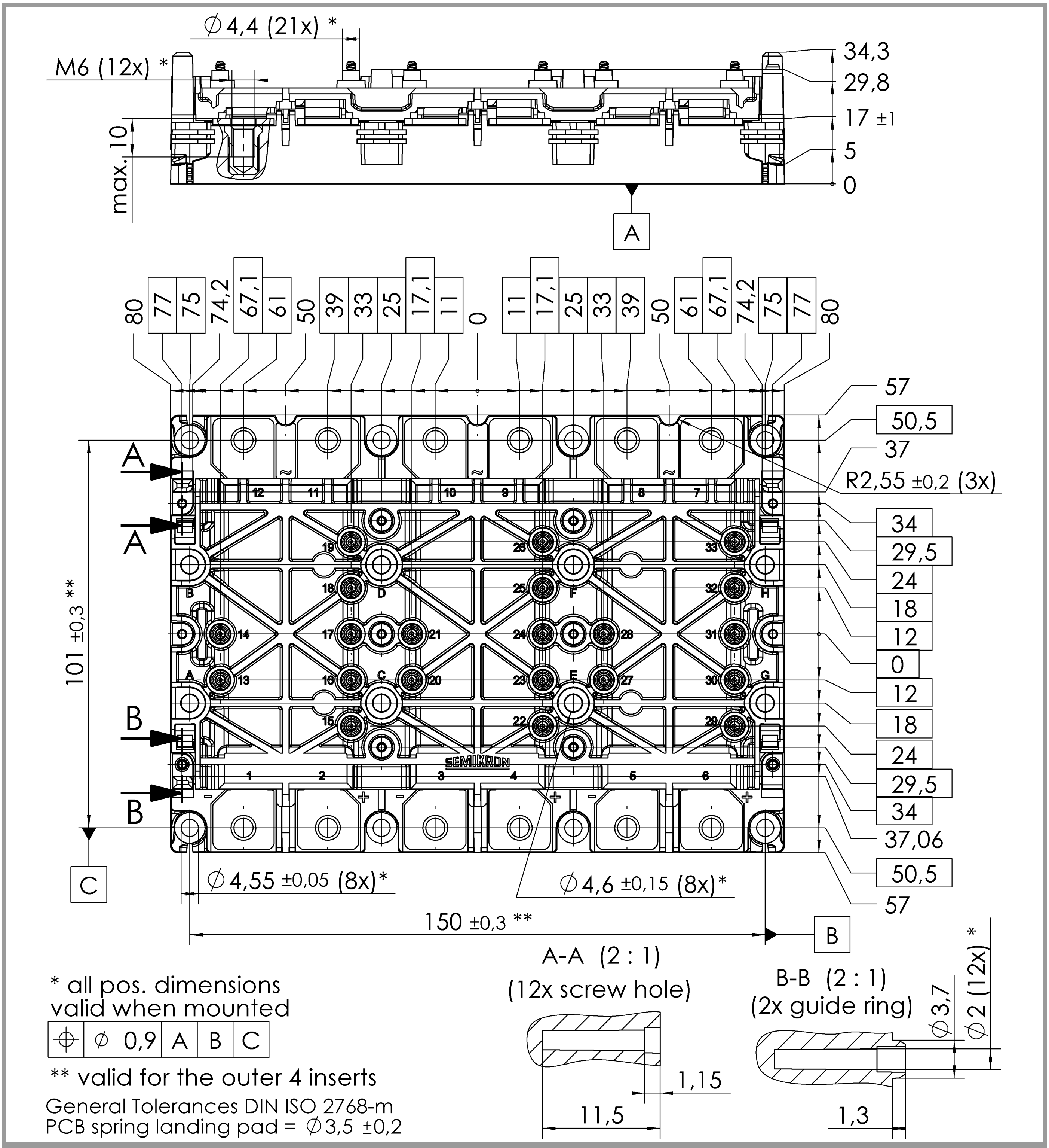
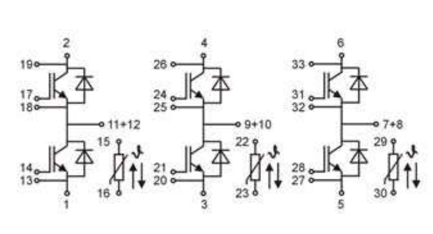


Fig. 12: Typ. CAL diode recovery charge



∅4,4 (21x) *
M6 (12x) *
max. 10
34,3
29,8
17 ±1
5
0
A
80
77
75
74,2
67,1
61
50
39
33
25
17,1
11
0
11
17,1
25
33
39
50
61
67,1
74,2
75
77
80
57
50,5
37
R2,55 ±0,2 (3x)
34
29,5
24
18
12
0
12
18
24
29,5
34
37,06
50,5
57
101 ±0,3 **
C
B
∅4,55 ±0,05 (8x)*
∅4,6 ±0,15 (8x)*
150 ±0,3 **
SEMIKRON
A-A (2 : 1)
(12x screw hole)
1,15
11,5
B-B (2 : 1)
(2x guide ring)
∅3,7
∅2 (12x) *
1,3
* all pos. dimensions
valid when mounted
∅ 0,9 A B C
** valid for the outer 4 inserts
General Tolerances DIN ISO 2768-m
PCB spring landing pad = ∅3,5 ±0,2



2
19
17
18
11+12
15
14
13
16
1
4
26
24
25
9+10
22
21
20
23
3
6
33
31
32
7+8
29
28
27
30
5

GD

This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, chapter IX.

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